

产品概览

BELASIGNA R262: 宽带声音捕获和降噪 SoC

欲看完整文档，请参阅数据表。

BelaSigna® R262 是一款完整的片上系统 (SoC) 方案，在移动电话等声音捕获设备中、网络广播和平板电脑等 VoIP 应用、双向无线电以及可由于改善的声音清晰度而受益的其他应用中提供宽带单麦克风或双麦克风降噪。该芯片具有新型的机械、稳定噪声和非稳定噪声去除方法，可以保护声音自然性，提高语音智能度，而不管使用时的声音环境或手持设备的朝向如何 — 为最终用户提供无与伦比的移动自由度。BelaSigna R262 设计可兼容多种编解码器、基带芯片和麦克风，无需校准或外部组件，它易于集成，缩短了制造商的“面市时间”。其他功能还包括去混响、自定义多种语音捕获模式和输出，并且能够对算法进行微调，以适应制造商设备的独特需求。该芯片包括一个高度优化的基于 DSP 的应用控制器，具有行业领先的能效，采用高度紧凑型 5.3 mm² WLCSP，适合空间最受限的工业设计。BelaSigna R262 的评估硬件和定制微调要求通过 Exaudio AB 提供。

特性

- Easy to integrate: Drop-in hardware and software solution that works without special tuning, calibration or external components
- Versatile voice capture: Consistently captures voice regardless of acoustic environment or orientation of the device while in use
- Design flexibility: Adaptive nature of algorithm enables flexibility in microphone placement and eliminates production line tuning; compatible with a broad range of microphones
- Advanced noise reduction: Effective against stationary and non-stationary background noise to improve voice clarity while preserving intelligibility and voice naturalness
- Simplified system integration: Complete System-on-Chip takes two microphone signals and plugs directly into a digital microphone interface (DMIC) or into a host chip's microphone inputs
- 360 degree voice pick-up: Conference mode clearly captures distant voices up to 6 meters from voice capture device
- Configurable system: Available PC-based tool provides easy control over all system settings
- Energy efficient: Ultra-low power consumption allows longer operation in active and standby modes without sacrificing performance
- Miniature size: Easily integrates into existing industrial designs due to minimal board area requirements

终端产品

器件电气规格

产品	Pricing (\$/Unit)	Compliance	Status	DSP Core (bits)	Coprocesor Type	MIPS	Dynamic Range (dB)	RAM (kB)	I _{standby} Typ (µA)	Audio Inputs	Audio Outputs	Package Type
BR262W26A103E1G		Pb-free Halide free	Active	16	WOLA	60	88	-	40	2	2	WLCSP-26

应用框图

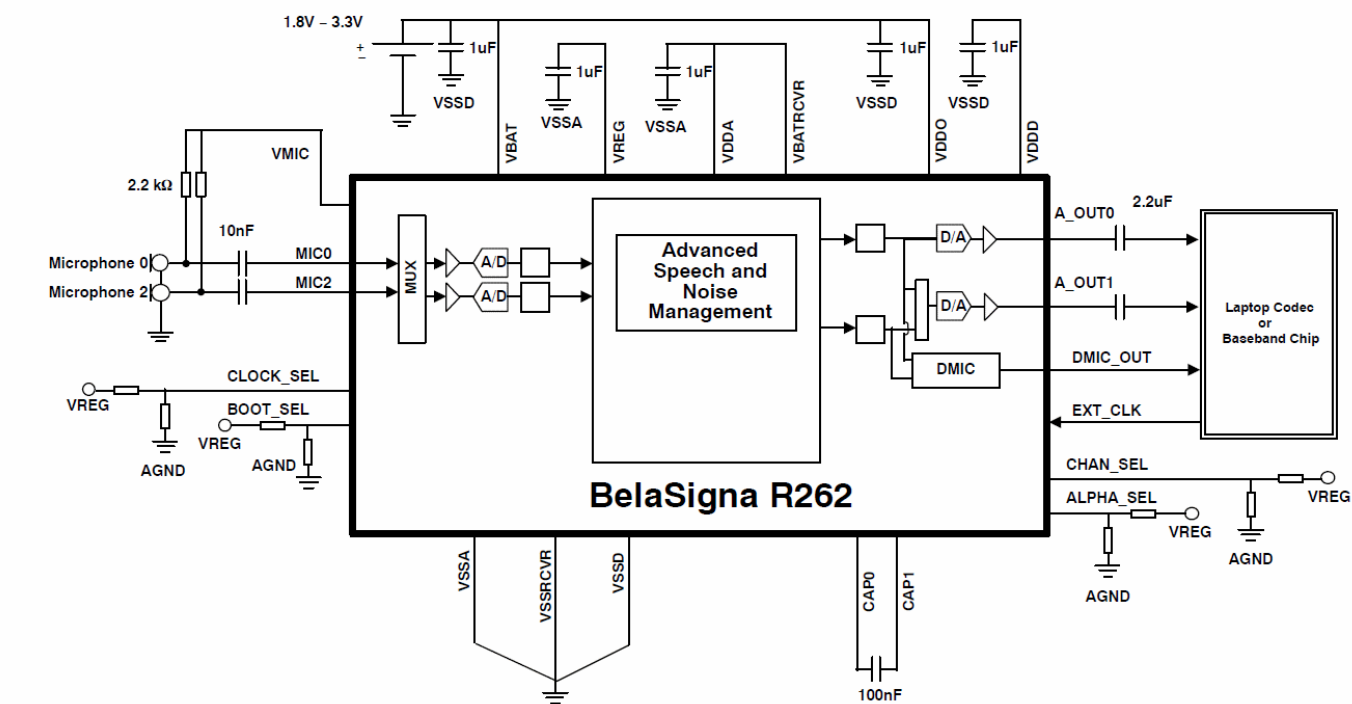


Figure 1. Typical Application Diagram for 30-ball WLCSP Package Option

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